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DDR4 DIMM Connector, 0.85mm PITCH**[Customer drawing](#)[Product Environmental Compliance Report](#)[Specifications](#)[Download document](#)

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Number of contacts (Total)	288
Product Type	DDR4
Memory Key Side	right
Insertion Style	Direct
Mating half	The mated module meets JEDEC Specification MO-309
Number of ejectors	2
Number of slots	1
Series Number	10124632

Dimensional

Height (Above board)	21.3 mm (0.839 in.)
Length (Tail)	2.95 mm (0.116 in.)
Spacing (Center line)	0.85 mm (0.0335 in.)

Electrical

Withstanding Voltage	500V AC rms
Current rating	0.75A @ 30°C
Resistance (Contact)	10 milli ohms
Resistance (Insulation)	1 M-ohms min.
Voltage rating	1.2 V

Mechanical

Durability (Mating cycles)	25 Mating Cycles
Retention force (Contact)	2.94N (300g)

Physical

Color (Ejector)	Natural
Color (Housing)	Natural
Material (Contact)	Copper Alloy
Material (Housing)	Thermoplastic (UL 94 V-O)
Plating (Contact area)	0.76 µm (30 µin.) Gold
Plating (Tail)	2.54 µm (100 µin.) Tin
Underplating (Contact)	1.27 µm (50 µin.) Nickel
Hold Down	Forklock
Operating Voltage	1.2V
Plating (Hold-down)	2.00 µm (80 µin.) Tin
Temperature (Operating - continuous)	+65°C
Temperature (Range)	-55°C to +65°C

Approvals / Certifications

Approvals / Certifications	In Process
Standards	JEDEC MO-309

Mounting

Alignment pegs	No
Mounting style	Board Through - Mount
Retention feature (Board)	Yes
Solder process	Wave

Other Features

Packaging (Type)	Soft tray
Form Factor	Standard

Disclaimer : The information above is for reference only. For more technical details, refer to product specification and application specification.